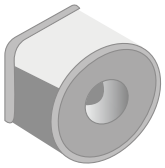
FEATURES

- Surface Mounting Design 5.4*5.4*4.0mm
- High Current Handling Capability 5000A @ 8/20 μs
- Low Capacitance and Insertion Loss
- Quick Response and Long Service Life
- Moisture sensitivity level：Level 1



5.4*5.4*4.0mm

Schematic Symbol

APPLICATION INFORMATION

- Communication equipment.
- Repeaters,Modems
- Telephone Interface,Line cards.
- Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
Pb	Mean lead free
®UL	UL Certificated E505857

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Spark-over Voltage 1)	100V/s	120-180	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ⩽650	
	At 1kV/μs	Typical values of distribution ⩽600	
Discharge Current (8/20us) 2)	10 times	5	KA
AC Discharge Current	50Hz, 1S	5	A
Minimum Insulation Resistance	Test Voltage DC=50V	1	GΩ
Max. Capacitance 1MHz	VDC=0.5V	1	pF
Operating and Storage Temperature		-40~125	°C

1) In ionized mode
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

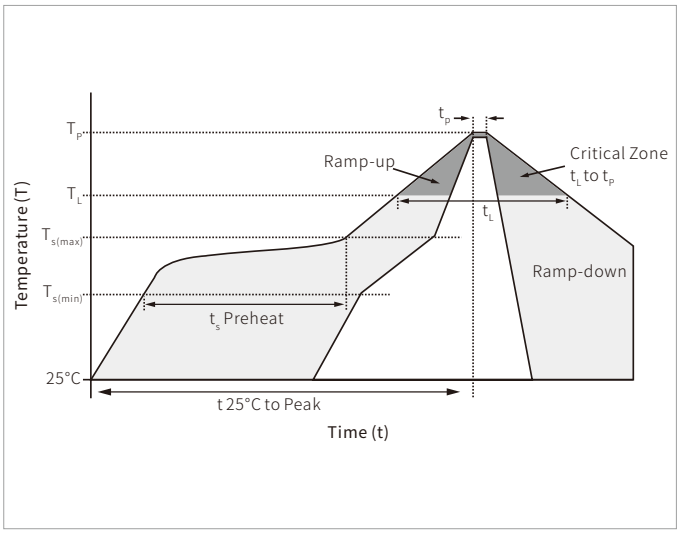
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude：0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering：10s，1time

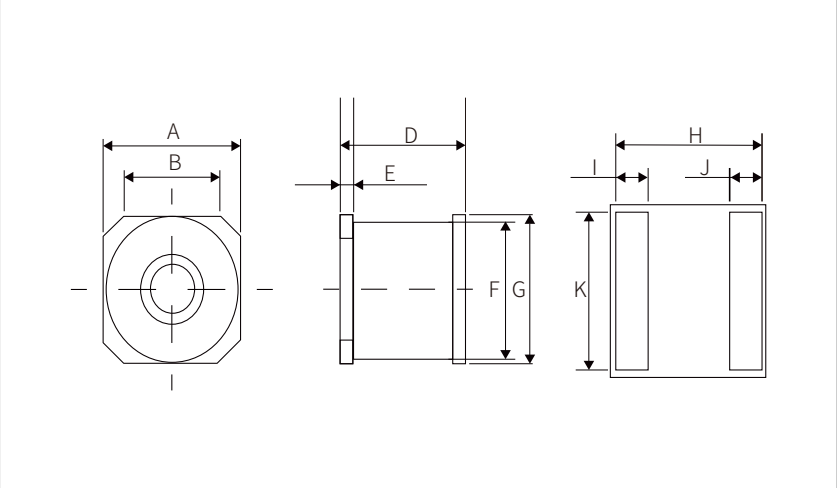
NOTE: Up-screen program can be specified by customer' s request via contacting Semiware service

SOLDERING PARAMETERS

Reflow Condition		Lead–free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes max.
Do not exceed		260°C

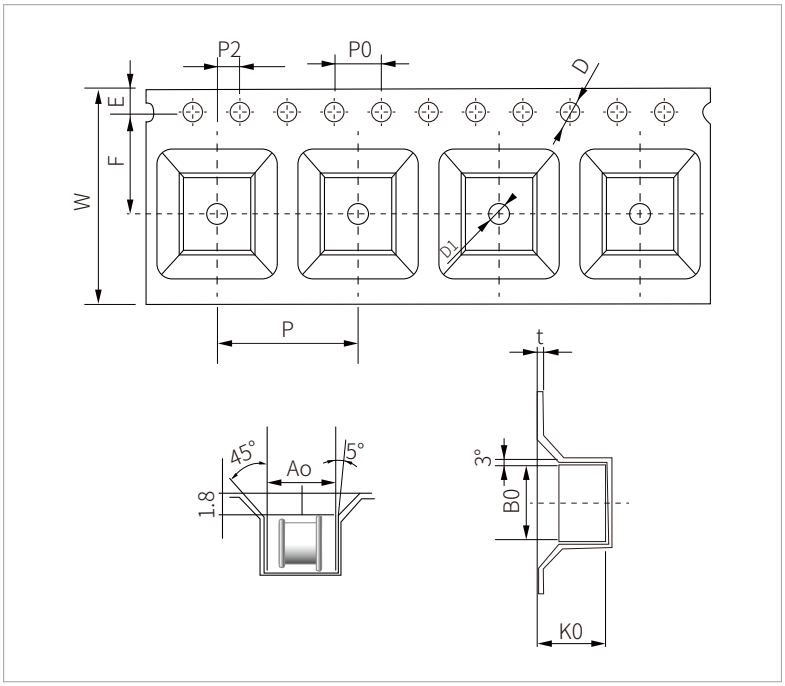


DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	mm
A	5.4±0.15
B	3.8
C	Φ6.6±0.2
D	4.0±0.2
E	0.5±0.1
F	Φ4.7±0.2
G	Φ5.4±0.15
H	4.7
I	1.3
J	1.3
K	3.9

PACKAGE REEL INFORMATION



Ref.	mm
W	16.0±0.3
P	12.0±0.1
E	1.75±0.1
F	7.5±0.1
P2	2.0±0.1
D	1.5±0.1
D1	1.5±0.1
P0	4.0±0.1
10P0	40.0±0.2
A0	5.7±0.1
B0	5.7±0.1
K0	5.7±0.1
t	0.4±0.05

ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
SG2R05B150B	5.4*5.4*4.0mm	SG150 05	800	13”

Headquarters
No.3387 Shendu Road
Pujiang I&E Park
Minhang Shanghai China
201000

Hotline
400-021-5756

Web
Https://www.semiware.com

Sales Center
Tel: 86-21-3463-7458
Email: sales18@semiware.com

Customer Service
Tel: 86-21-5484-1001
Email: sales17@semiware.com

Technical Support
Tel: 86-21-3463-7654
Email: fae01@semiware.com

Complaint & Suggestions
Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

By QR Code
Website
Wechat

To find your local partner within Semiware' s global website: www.semiware.com